

Consultation No. 1 Lead in tin whisker resistant coatings for fine pitch applications

No.7 Lead in connectors, flexible printed circuits, flexible flat cables

JBCE(Japan Business Council in Europe)

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We, JBCE, support the following two comments concerning items No. 1 and No. 7, both of which belong to the category of tin whisker problems in electronics areas.

a) JEITA's (Japan Electronics & Information Technology Industries Association) comments on "Lead in connectors, flexible printed circuits, flexible flat cables".(item No. 7)

(Precise wording)

"Lead in lead surface plating on flexible printed circuit, flexible flat cables and their connectors"

b) Fujitsu's comments on "Lead in tin whisker resistant coatings for fine pitch applications"(item No. 1)

(Precise wording)

"Lead in tin whisker resistant coatings for electronic components requiring a thin solderable coating with a maximum of 15wt% . Pb in the coating provided that the spacing between conductive leads is less than 400 micrometers or with a component lead pitch up to 800 micrometers(0.8mm)."

(Reason)

We, JBCE, raised general tin whisker problems last September in the form of check-list and have so far found that recent technology development is expected to contribute to solve most of these problems.

We understand there still exists tin whisker problems in some electronics areas. But we also have found that some of them had already obtained future exemption, for example "compliant pin connectors" and "servers and network equipment" whose main problems are tin whisker.

We believe that the main areas which remain to be solved by urgent exemption are those mentioned above. This is the reason why we modified from our previous general position last September.